


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	MICROCONTROLLERS/25/15172	
1.3 Title of PCI	AMKOR ATP (Philippines) - UBoT Carrier Tape & Cover Tape alternative packing material for TQFP20x20 144L package on listed products.	
1.4 Product Category	STM32F1x, STM32F2x, STM32F4x, STM32F7x, STM32H7x, STM32L1x, STM32L4x in Tape & Reel packing	
1.5 Issue date	2025-02-25	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New Indirect material part number (same supplier or different supplier): Boxes, trays, carriers, back grinding tape, wafer mounting tape, mold tape, etc..	AMKOR (Philippines)

4. Description of change

	Old	New
4.1 Description	Current supplier: KOSTAT - Cover tape and Carrier tape with pedestal & Partial fence	New supplier: UBoT - Cover tape and Carrier tape with pedestal & with Full fence guide
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact as no change on products.	

5. Reason / motivation for change

5.1 Motivation	Alternate Tape and Reel material with a more robust design to help prevent bent leads during reel handling
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2025-01-14
7.2 Intended start of delivery	2025-04-14
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description	15172 GPAM-qualification.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2025-02-25
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9. Attachments (additional documentations)
15172 Public product.pdf 15172 GPAM-qualification.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F103ZET6TR	
	STM32F103ZGT6TR	
	STM32F205ZCT6TR	
	STM32F205ZCT7TR	
	STM32F205ZET6TR	
	STM32F205ZGT6TR	
	STM32F207ZET6TR	
	STM32F207ZGT6TR	
	STM32F405ZGT7TR	
	STM32F407ZET6TR	
	STM32F407ZGT6TR	
	STM32F412ZGT6TR	
	STM32F427ZGT6TR	
	STM32F427ZIT6TR	
	STM32F429ZGT6TR	
	STM32F429ZIT6TR	
	STM32F437ZIT7TR	
	STM32F722ZET6TR	
	STM32F765ZGT6TR	
	STM32F765ZIT7TR	
	STM32H753ZIT6TR	
	STM32L476ZET6TR	
	STM32L476ZGT6TR	
	STM32L496ZET6TR	
	STM32L496ZGT6TR	

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